ARTICLES

Effect of copper emitted from wafers on etch rates of insulator films in capacitively coupled fluorocarbon plasma
Shin-ichi Imai
J. Vac. Sci. Technol. A **27**, 1 (2009); http://dx.doi.org/10.1116/1.3006029
+ VIEW DESCRIPTION

Ultrahigh-frequency microplasma jet as a low-power, high-density, and localized ions/radicals source
Hiroyuki Miyazoe, Masaki Sai, Sven Stauss and Kazuo Terashima
J. Vac. Sci. Technol. A **27**, 9 (2009); http://dx.doi.org/10.1116/1.3010716
+ VIEW DESCRIPTION

Effect on plasma and etch-rate uniformity of controlled phase shift between rf voltages applied to powered electrodes in a triode capacitively coupled plasma reactor
Dougyong Sung, Sangmin Jeong, Youngmin Park, Vladimir N. Volynets, Andrey G. Ushakov and Gon-Ho Kim
J. Vac. Sci. Technol. A **27**, 13 (2009); http://dx.doi.org/10.1116/1.3010717
+ VIEW DESCRIPTION

Numerical study of the sputtering in a dc magnetron
Ivan Kolev and Annemie Bogaerts
J. Vac. Sci. Technol. A **27**, 20 (2009); http://dx.doi.org/10.1116/1.3013856
+ VIEW DESCRIPTION

Growth and characterization of $TiAlN/CrAlN$ superlattices prepared by reactive direct current magnetron sputtering
Harish C. Barshilia, B. Deepthi, K. S. Rajam, Kanwal Preet Bhatti and Sujeet Chaudhary
J. Vac. Sci. Technol. A **27**, 29 (2009); http://dx.doi.org/10.1116/1.3013858
+ VIEW DESCRIPTION

Plasma atomic layer etching using conventional plasma equipment
Ankur Agarwal and Mark J. Kushner
J. Vac. Sci. Technol. A **27**, 37 (2009); http://dx.doi.org/10.1116/1.3021361
+ VIEW DESCRIPTION

Selective formation of competitive c-axis and a-axis oriented $LiNbO_3$ epitaxial films on $Al_2O_3(11\bar{2}0)$
Housei Akazawa
J. Vac. Sci. Technol. A **27**, 51 (2009); http://dx.doi.org/10.1116/1.3021365
+ VIEW DESCRIPTION

Analysis of surface roughness and its relationship with photoluminescence properties of silicon-rich oxide films

J. A. Luna-López, A. Morales-Sánchez, M. Aceves-Mijares, Z. Yu and C. Domínguez
J. Vac. Sci. Technol. A **27**, 57 (2009); http://dx.doi.org/10.1116/1.3032915

+ VIEW DESCRIPTION

Crystallographic texture control of sputtered HfN thin films using low oxygen partial pressures
D. Deniz and J. M. E. Harper
J. Vac. Sci. Technol. A **27**, 63 (2009); http://dx.doi.org/10.1116/1.3039680

+ VIEW DESCRIPTION

Second-order resonant ZnO-based film bulk acoustic resonator devices and thermal techniques to improve their resonant characteristics
Linh Mai, Van-Su Pham and Giwan Yoon
J. Vac. Sci. Technol. A **27**, 67 (2009); http://dx.doi.org/10.1116/1.3039681

+ VIEW DESCRIPTION

Tritium gas flow dynamics through the source and transport system of the Karlsruhe tritium neutrino experiment
O. B. Malyshev, Chr. Day, X. Luo and F. Sharipov
J. Vac. Sci. Technol. A **27**, 73 (2009); http://dx.doi.org/10.1116/1.3039679

+ VIEW DESCRIPTION

Nanocomposite TiSiN coatings deposited by large area filtered arc deposition
Y. H. Cheng, T. Browne and B. Heckerman
J. Vac. Sci. Technol. A **27**, 82 (2009); http://dx.doi.org/10.1116/1.3043460

+ VIEW DESCRIPTION

Computational and experimental study of gas flows through long channels of various cross sections in the whole range of the Knudsen number
Stelios Varoutis, Steryios Naris, Volker Hauer, Christian Day and Dimitris Valougeorgis
J. Vac. Sci. Technol. A **27**, 89 (2009); http://dx.doi.org/10.1116/1.3043463

+ VIEW DESCRIPTION

Photoluminescence from Er-doped Si-rich Si oxides deposited by magnetron sputtering in Ar or $Ar + H_2$ plasmas
C. L. Heng, E. Chelomentsev, O. H. Y. Zalloum, J. Wojcik and P. Mascher
J. Vac. Sci. Technol. A **27**, 101 (2009); http://dx.doi.org/10.1116/1.3043465

+ VIEW DESCRIPTION

Effects of deposition parameters on tantalum films deposited by direct current magnetron sputtering
Y. M. Zhou, Z. Xie, H. N. Xiao, P. F. Hu and J. He
J. Vac. Sci. Technol. A **27**, 109 (2009); http://dx.doi.org/10.1116/1.3046143

+ VIEW DESCRIPTION

Dilute hydrogen plasma cleaning of boron from silicon after etching of HfO_2 films in BCl_3 plasmas: Substrate temperature dependence

Chunyu Wang and Vincent M. Donnelly

J. Vac. Sci. Technol. A **27**, 114 (2009); http://dx.doi.org/10.1116/1.3054131

+ VIEW DESCRIPTION

Oxidation of $^{13}C_2H_5OH$ by NO and O_2 on the surface of stepped Pt(332): Relationship to selective catalytic reduction of NO with hydrocarbons

Yuhai Hu, Peter Norton and Keith Griffiths

J. Vac. Sci. Technol. A **27**, 121 (2009); http://dx.doi.org/10.1116/1.3054132

+ VIEW DESCRIPTION

Profile evolution simulator for sputtering and ion-enhanced chemical etching

J. Saussac, J. Margot and M. Chaker

J. Vac. Sci. Technol. A **27**, 130 (2009); http://dx.doi.org/10.1116/1.3054134

+ VIEW DESCRIPTION

Heavy-ion induced desorption of a TiZrV coated vacuum chamber bombarded with $5MeV/u\ \ Ar^{8+}$ beam at grazing incidence

E. Hedlund, O. B. Malyshev, L. Westerberg, A. Krasnov, A. S. Semenov, M. Leandersson, B. Zajec, H. Kollmus, M. C. Bellachioma, M. Bender, A. Krämer and H. Reich-Sprenger

J. Vac. Sci. Technol. A **27**, 139 (2009); http://dx.doi.org/10.1116/1.3032914

+ VIEW DESCRIPTION

Characterization of low-temperature silicon nitride films produced by inductively coupled plasma chemical vapor deposition

Q. Xu, Y. Ra, M. Bachman and G. P. Li

J. Vac. Sci. Technol. A **27**, 145 (2009); http://dx.doi.org/10.1116/1.3054133

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ARTICLES

Feedback control of plasma electron density and ion energy in an inductively coupled plasma etcher
Chaung Lin, Keh-Chyang Leou, Hong-Min Huang and Cheng-Hung Hsieh
J. Vac. Sci. Technol. A **27**, 157 (2009); http://dx.doi.org/10.1116/1.3054135

+ VIEW DESCRIPTION

ERRATA

Erratum: Copper ion transport induced dielectric failure: Inclusion of elastic drift and consequences for reliability [J. Vac. Sci. Technol. A 26, 1497 (2008)]
Ravi S. Achanta, Joel L. Plawsky and William N. Gill
J. Vac. Sci. Technol. A **27**, 165 (2009); http://dx.doi.org/10.1116/1.3054138

+ VIEW DESCRIPTION